

10-3170

ONE COMPONENT EPOXY

DESCRIPTION:

10-3170 is a one component heat curing epoxy system. Unlike many one part epoxy systems, 10-3170 can be cured at moderately low temperatures. Due to its ability to cure at low temperatures, this system can be utilized in numerous applications where higher temperature curing systems were prohibited.

10-3170 offers very high operating temperature properties, thermal shock resistance, and excellent electrical insulation properties. 10-3170 can be used as an adhesive, sealant, barrier coating or encapsulating compound.

FEATURES:

No mixing or weighing
Excellent adhesion
Unlimited pot life

TYPICAL SPECIFICATIONS:

Viscosity @ 25C cps	120,000
Gel time, min @ 100°C	5.00
Gel time, min @ 150°C	1.00
Specific Gravity, 25°C/25°C	1.1
Shelf life @ 25°C, mos.	6.0
Tensile Strength @ 25°C, psi	4,000
Dielectric Strength, Volts/Mil	490
Dielectric Constant, 60 Hz	3.8
Volume Resistivity, OHM-CM	1.4×10^{16}
Modules of elasticity, psi	5.0×10^5
Machinability	Excellent
Operating temperature range	-60 to 175°C
Heat distortion temperature, °C	110
Dissipation factor, 60 Hz	0.020



INSTRUCTIONS FOR USE:

Since 10-3170 is a one component system, no mixing of catalyst is required. It comes ready to use.

Apply by any convention method; i.e., spatula, dipping, brush, roller, pneumatically, etc...

Cure with any one of the following schedules:

4 to 5 hours at 100°C

2 to 3 hours at 125°C

10 to 15 minutes at 150°C

IMPORTANT:

The information in this brochure is based on data obtained by our own research and is considered accurate. However, no warranty is expressed or implied regarding the accuracy of these data, the results to be obtained from the use thereof, or that any such use will not infringe any patent. This information is furnished upon the condition that the person receiving it shall make his own tests to determine the suitability thereof for his particular purpose.

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